

# MBRB2060CT

Preferred Device

## SWITCHMODE™ Power Rectifier

### D<sup>2</sup>PAK Surface Mount Power Package

These state-of-the-art devices employ the use of the Schottky Barrier principle with a platinum barrier metal.

#### Features

- Package Designed for Power Surface Mount Applications
- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured – Not Sheared
- Similar in Size to Industry Standard TO-220 Package
- Pb-Free Packages are Available

#### Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)  
Human Body Model, 3B (>8000 V)

#### MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	60	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 110^\circ\text{C}$ ) Total Device	$I_{F(AV)}$	10 20	A
Peak Repetitive Forward Current (Rated $V_R$ , Square Wave, 20 kHz, $T_C = 100^\circ\text{C}$ )	$I_{FRM}$	20	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	150	A
Peak Repetitive Reverse Surge Current (2.0 $\mu\text{s}$ , 1.0 kHz)	$I_{RRM}$	0.5	A
Storage Temperature Range	$T_{stg}$	-65 to +175	°C
Operating Junction Temperature (Note 1)	$T_J$	-65 to +175	°C
Voltage Rate of Change (Rated $V_R$ )	dv/dt	10,000	V/ $\mu\text{s}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

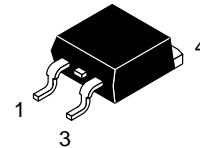
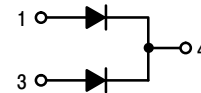
1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP/dT_J < 1/R_{\theta JA}$ .



ON Semiconductor®

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### SCHOTTKY BARRIER RECTIFIER 20 AMPERES, 60 VOLTS



D<sup>2</sup>PAK  
CASE 418B  
STYLE 3

#### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
B2060 = Device Code  
G = Pb-Free Package  
AKA = Diode Polarity

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

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## THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance, - Junction-to-Case - Junction-to-Ambient (Note 2)	$R_{\theta JC}$ $R_{\theta JA}$	2.0 50	$^{\circ}\text{C}/\text{W}$

2. When mounted using minimum recommended pad size on FR-4 board.

## ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ( $i_F = 20$ Amps, $T_J = 125^{\circ}\text{C}$ ) ( $i_F = 20$ Amps, $T_J = 25^{\circ}\text{C}$ )	$V_F$	0.85 0.95	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 125^{\circ}\text{C}$ ) (Rated dc Voltage, $T_J = 25^{\circ}\text{C}$ )	$i_R$	35 0.15	mA

3. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBRB2060CT	D <sup>2</sup> PAK	50 Units / Rail
MBRB2060CTG	D <sup>2</sup> PAK (Pb-Free)	50 Units / Rail
MBRB2060CTT4	D <sup>2</sup> PAK	800 Units / Tape & Reel
MBRB2060CTT4G	D <sup>2</sup> PAK (Pb-Free)	800 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

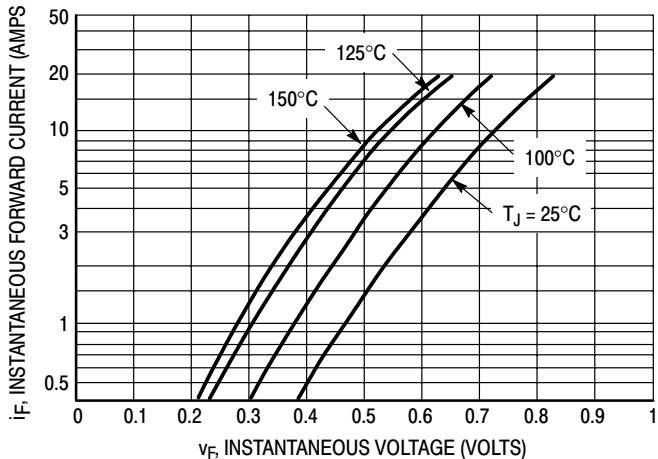


Figure 1. Typical Forward Voltage Per Diode

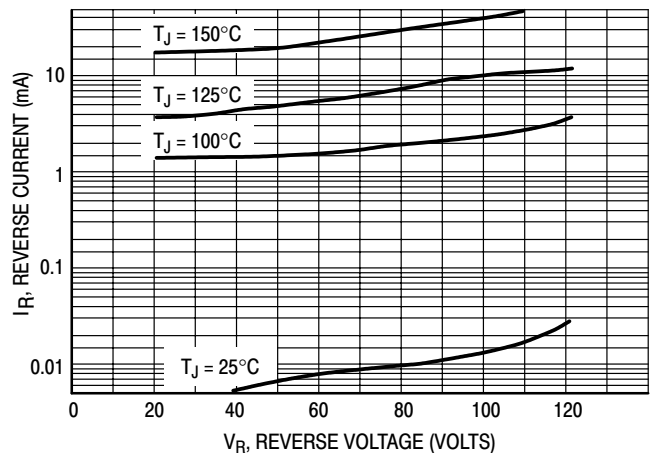


Figure 2. Typical Reverse Current Per Diode

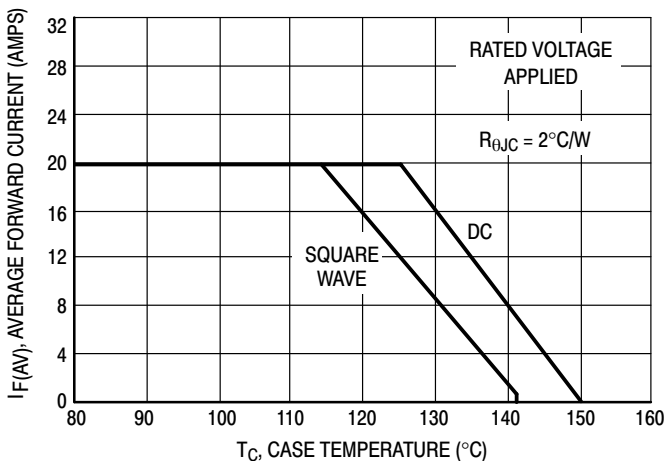


Figure 3. Typical Current Derating, Case, Per Leg

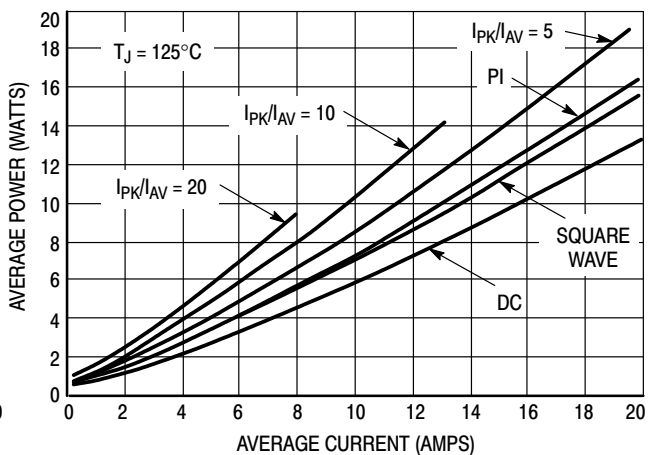
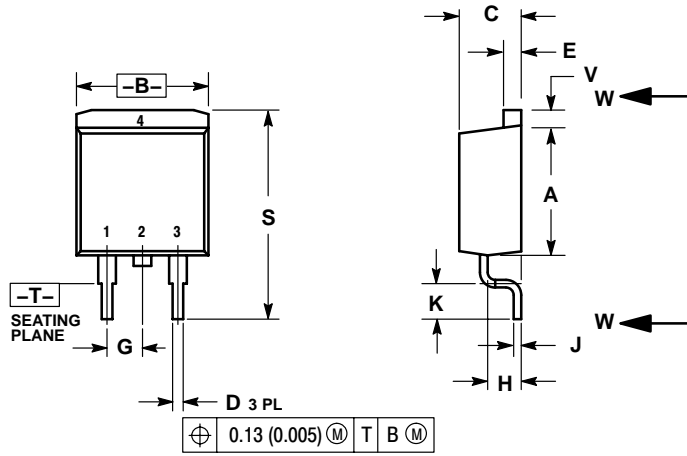


Figure 4. Average Power Dissipation and Average Current

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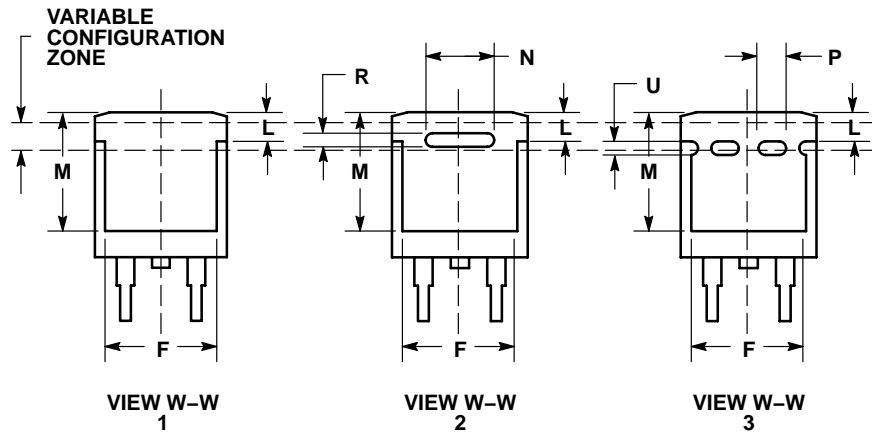
## PACKAGE DIMENSIONS

D<sup>2</sup>PAK 3  
CASE 418B-04  
ISSUE J



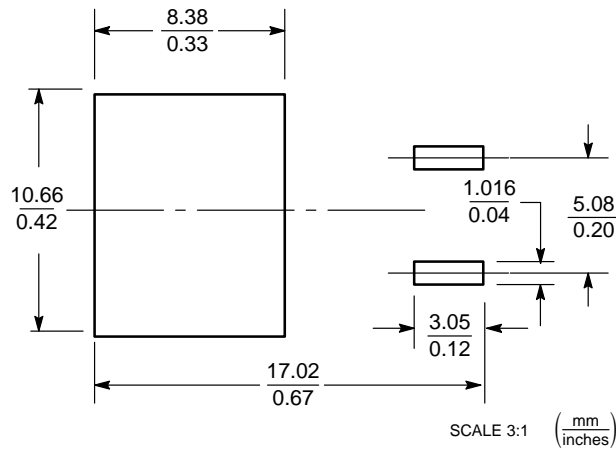
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54	BSC
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197	REF	5.00	REF
P	0.079	REF	2.00	REF
R	0.039	REF	0.99	REF
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



- STYLE 3:
- PIN 1. ANODE
  - CATHODE
  - ANODE
  - CATHODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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**MBRB2060CT/D**